



TECHNICAL DATA SHEET

Sn28Pb72 Solder Sticks

PRODUCTDESCRIPTION

PAI Sn28Pb72 solder sticks are being formulated with virgin raw metals processed in state-of-the-art Vaccumalloy Technology that brings world class quality along. Here, oxygen interaction with alloy is nil and thus, dross formation is reduced at PCB assembly or PCB manufacturing processes. Also an increased flow rate & reduced impurities found. PAI Sn28Pb72 is compatible with typical range of flux application formulas used in Electronics Industry today.

STORAGEANDHANDLING

- Do not use fire near storage area.
- Store in dry, cool and non-corrosive environment.
- Wear Personal Protective Equipments while handling.
- Wear Personal Protective Equipments while processing.

ALLOYCOMPOSITION

Sl. No	Metal	PAI Sn28Pb72 Solder Sticks	ISO9453 Specification	J-STD-006 Specification
1	Sn	28% min	27.5%~28.50%	27.5%~28.50%
2	Pb	Rem	Rem	Rem
3	Sb	0.05% max	0.05% max	0.5% max
4	Cu	0.05% max	0.05% max	0.08% max
5	Au	0.05% max	0.05% max	NA
6	Ag	0.10% max	NA	0.10% max
7	Al	0.001% max	0.001% max	0.005% max
8	As	0.03% max	0.03% max	0.03% max
9	Bi	0.05% max	0.05% max	0.25% max
10	Cd	0.002% max	0.002% max	0.001% max
11	In	0.003% max	NA	NA
12	Fe	0.02% max	0.02% max	0.02% max
13	Ni	0.01% max	NA	0.01% max
14	Zn	0.001% max	0.001% max	0.003% max
15	S	0.0004% max	NA	NA

PHYSICAL CHARACTERISTICS OF APPLICATION

Alloy	Sn28Pb72
Shape	Die Casting
Density	9.7gm/cm ³ at 20 ⁰ C
Solidus Temperature	183 ⁰ C
Liquidus Temperature	265 ⁰ C
Standard Package Quantity	25Kgs
Application	Special Processes
Standards Considered	JIS-Z-3282
Shelf Life	10 Years

Note: Refer in-house specifications for application factors.